

## Features

- Trench Power MOSFET
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free."Green" Device <sup>(Note 1)</sup>
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)
- Moisture Sensitivity Level 1

## Maximum Ratings

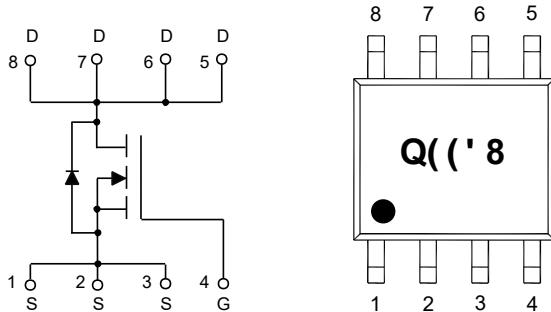
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 60°C/W Junction to Ambient<sup>(Note 2)</sup>

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V <sub>DS</sub>	60	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current	I <sub>D</sub>	8.2	A
		5	
Pulsed Drain Current <sup>(Note 3)</sup>	I <sub>DM</sub>	40	A
Total Power Dissipation <sup>(Note 4)</sup>	P <sub>D</sub>	2.1	W
Single Pulsed Avalanche Energy <sup>(Note 5)</sup>	E <sub>AS</sub>	72	mJ

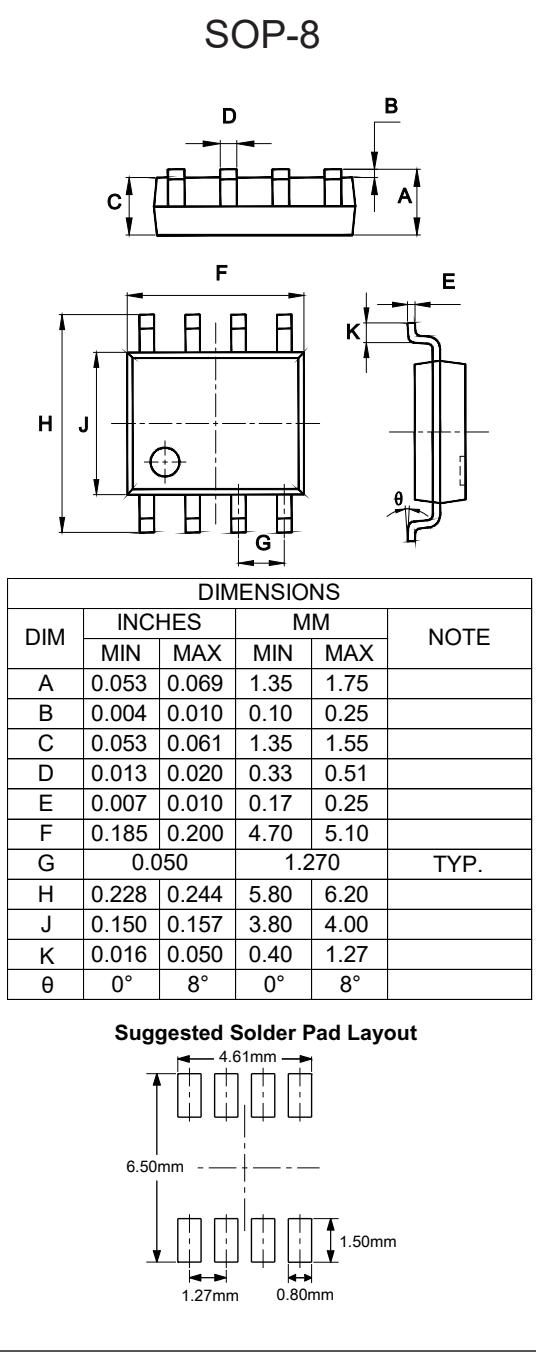
Note:

1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of R<sub>θJA</sub> is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C. The Power dissipation P<sub>DSM</sub> is based on R<sub>θJA</sub> t≤ 10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P<sub>D</sub> is based on max. junction temperature, using junction-Ambient thermal resistance.
5. T<sub>J</sub>=25°C, V<sub>DD</sub>=40V, V<sub>GS</sub>=10V, L=1mH.

## Internal Structure and Marking Code



## N-CHANNEL MOSFET



**Electrical Characteristics @ 25°C (Unless Otherwise Specified)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	60			V
Gate-Source Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS} = \pm 20V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=60V, V_{GS}=0V$			1	$\mu A$
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1		3	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=8.2A$		13	22	$m\Omega$
		$V_{GS}=4.5V, I_D=7.6A$		15.5	27	
Forward Tranconductance	$g_{fs}$	$V_{DS}=5V, I_D=8.2A$	10			S
Gate Resistance	$R_G$	f=1MHz, Open Drain		1.2		$\Omega$
<b>Dynamic Characteristics</b>						
Continuous Body Diode Current	$I_S$				8.2	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=8.2A$			1.2	V
Reverse Recovery Time	$t_{rr}$	$I_S=20A, di/dt=100A/\mu s$		24		ns
Reverse Recovery Charge	$Q_{rr}$			23		nC
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=30V, V_{GS}=0V, f=1MHz$		2306		$pF$
Output Capacitance	$C_{oss}$			126		
Reverse Transfer Capacitance	$C_{rss}$			104		
Total Gate Charge(10V)	$Q_g$	$V_{DS}=30V, V_{GS}=10V, I_D=8.2A$		45		$nC$
Gate-Source Charge	$Q_{gs}$			5		
Gate-Drain Charge	$Q_{gd}$			9		
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=10V, V_{DS}=30V, R_L=3.6\Omega, R_{GEN}=3\Omega$		8.8		$ns$
Turn-On Rise Time	$t_r$			11		
Turn-Off Delay Time	$t_{d(off)}$			36		
Turn-Off Fall Time	$t_f$			7.7		

Fig. 1 - Typical Output Characteristics

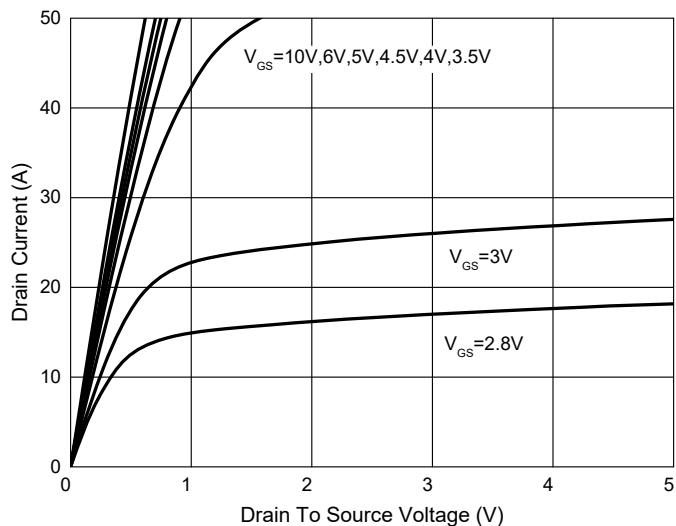


Fig. 2 - Transfer Characteristics

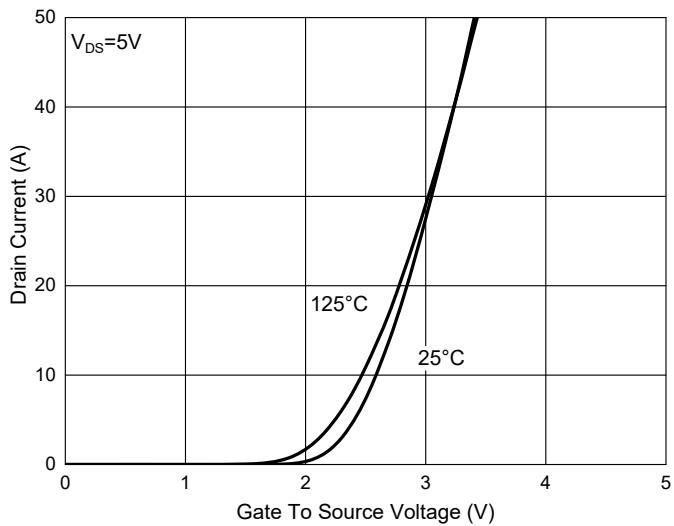


Fig. 3 -  $R_{DS(ON)}$ — $V_{GS}$

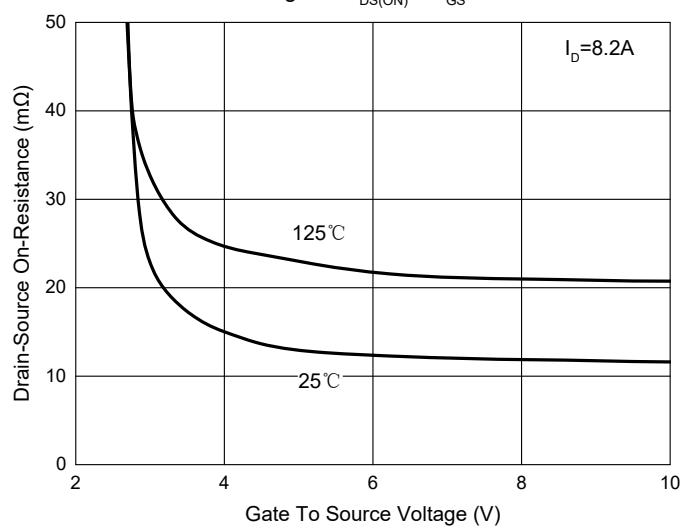


Fig. 4 -  $R_{DS(ON)}$ — $I_D$

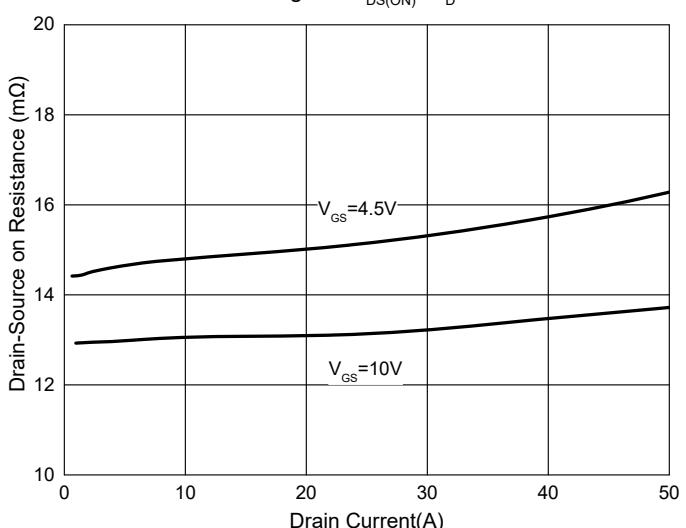


Fig. 5 - Capacitance Characteristics

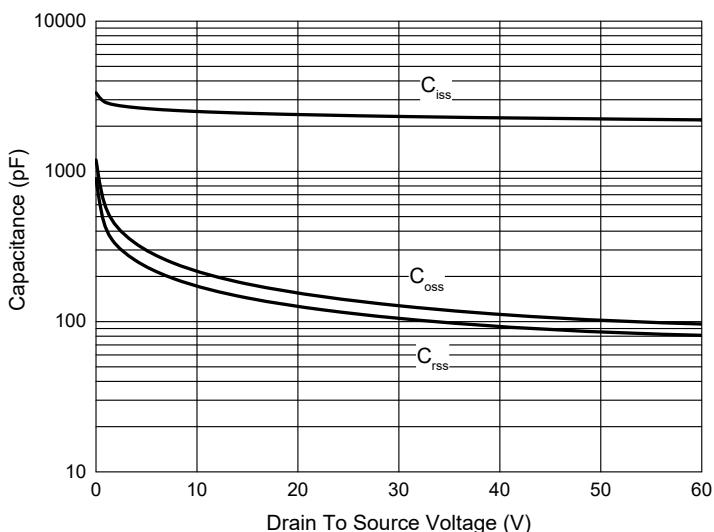
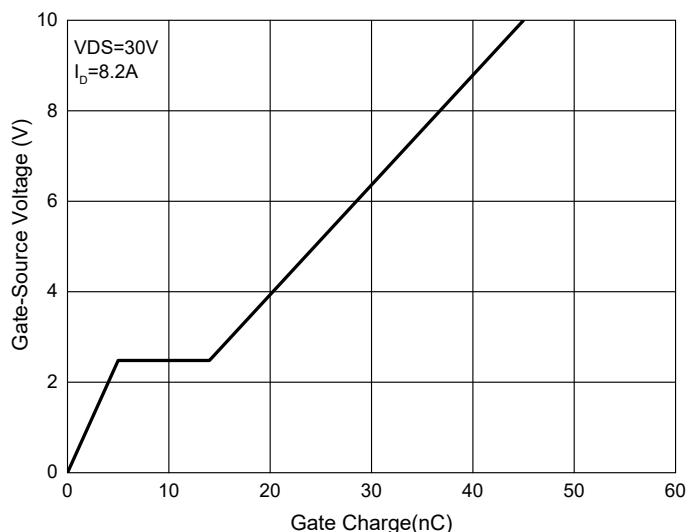


Fig. 6 - Gate Charge



## Curve Characteristics

Fig. 7 - Normalized On Resistance Characteristics

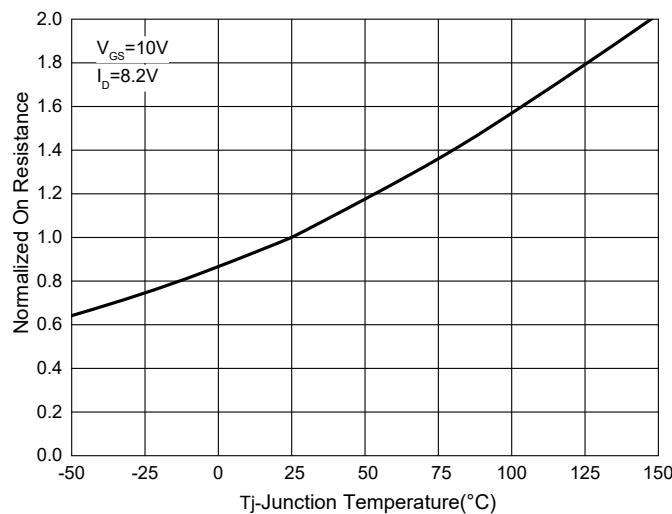


Fig. 8 - Normalized Threshold voltage

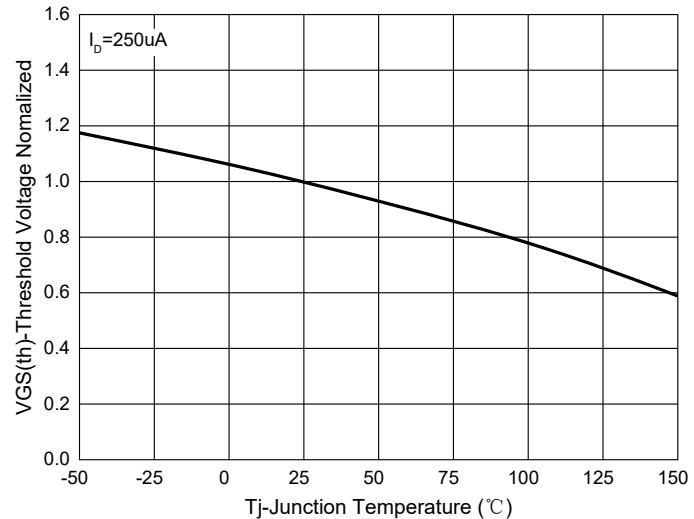


Fig. 9 -  $I_S$ — $V_{SD}$

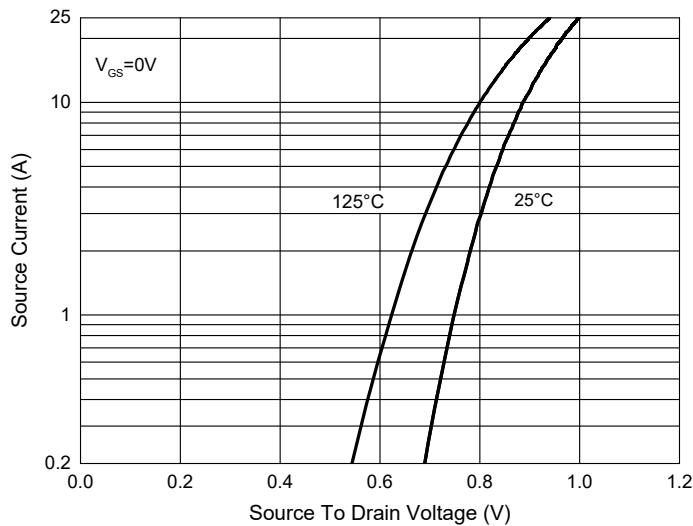


Fig. 10 - Drain Current

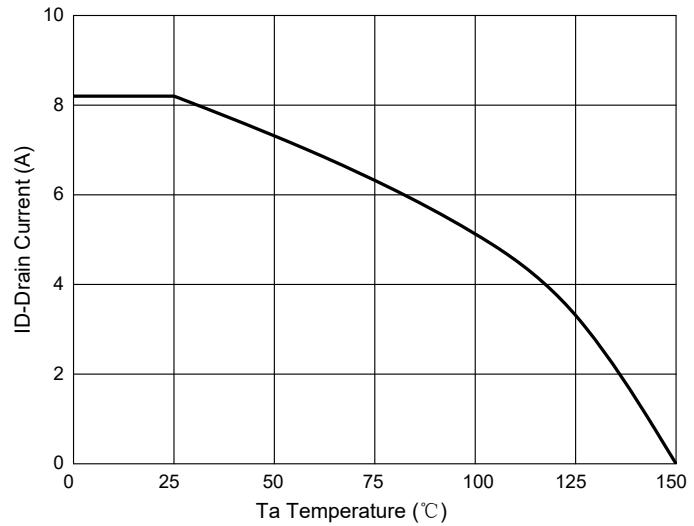
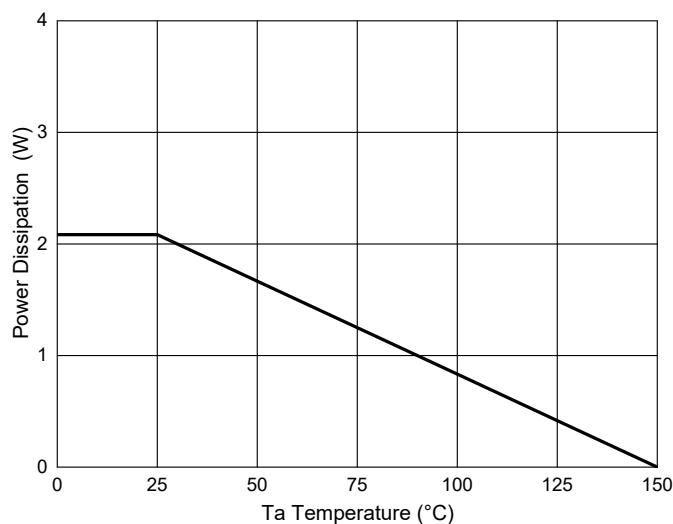


Fig. 11-PD Dissipation



## Curve Characteristics

Fig. 12 - Safe Operation Area

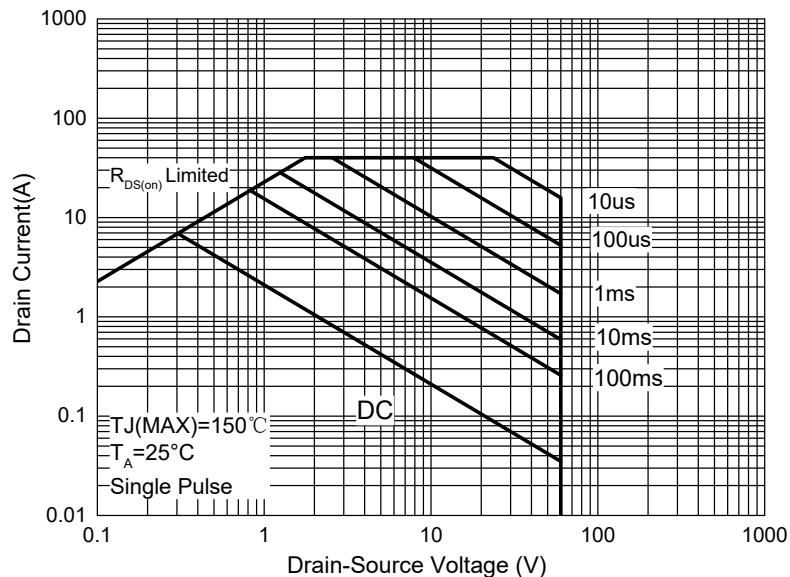
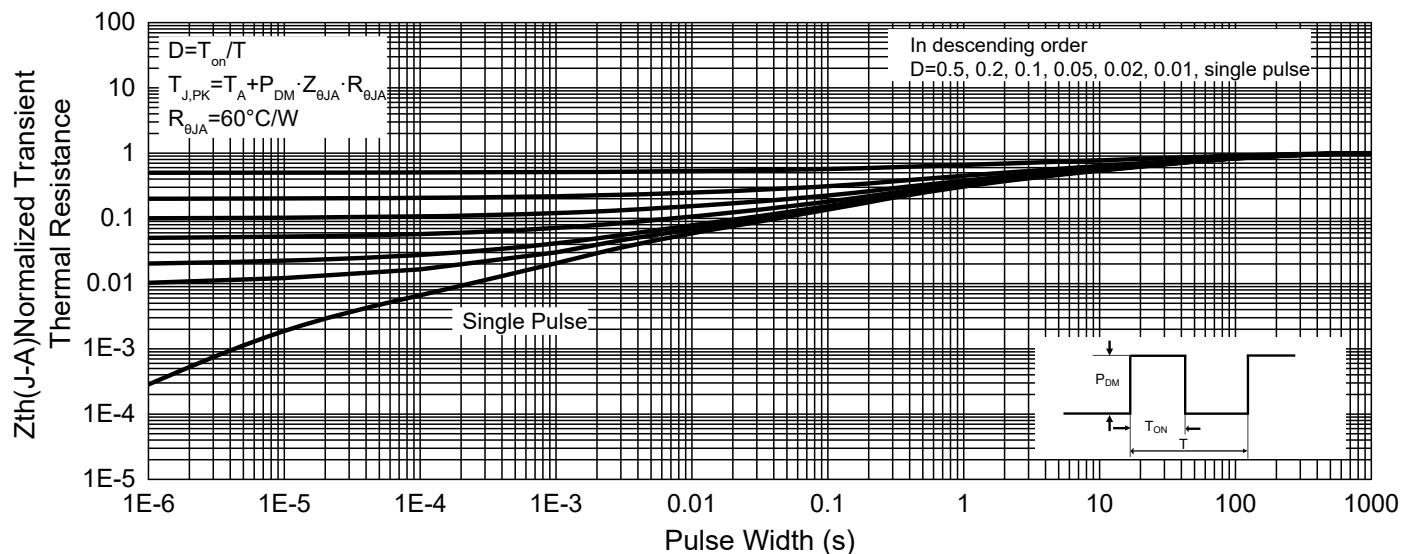


Fig. 13 - Normalized Transient Thermal Impedance



## Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 4Kpcs/Reel

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